

查询"8551901EA"供应商

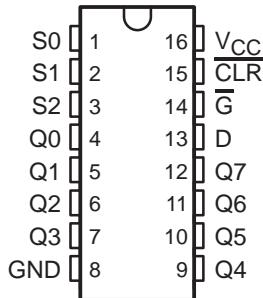
SCLS134E – DECEMBER 1982 – REVISED SEPTEMBER 2003

- Wide Operating Voltage Range of 2 V to 6 V
- High-Current Inverting Outputs Drive Up To 10 LSTTL Loads
- Low Power Consumption, 80- μ A Max I_{CC}
- Typical $t_{pd} = 14$ ns
- ± 4 -mA Output Drive at 5 V
- Low Input Current of 1 μ A Max
- 8-Bit Parallel-Out Storage Register Performs Serial-to-Parallel Conversion With Storage
- Asynchronous Parallel Clear
- Active-High Decoder
- Enable Input Simplifies Expansion
- Expandable for n-Bit Applications
- Four Distinct Functional Modes

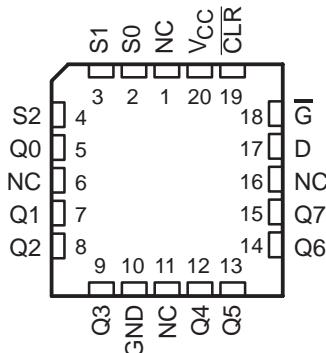
description/ordering information

These 8-bit addressable latches are designed for general-purpose storage applications in digital systems. Specific uses include working registers, serial-holding registers, and active-high decoders or demultiplexers. They are multifunctional devices capable of storing single-line data in eight addressable latches and being a 1-of-8 decoder or demultiplexer with active-high outputs.

SN54HC259 . . . J OR W PACKAGE
SN74HC259 . . . D, N, NS, OR PW PACKAGE
(TOP VIEW)



SN54HC259 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

ORDERING INFORMATION

TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube of 25	SN74HC259N	SN74HC259N
	SOIC – D	Tube of 40	SN74HC259D	HC259
		Reel of 2500	SN74HC259DR	
		Reel of 250	SN74HC259DT	
	SOP – NS	Reel of 2000	SN74HC259NSR	HC259
	TSSOP – PW	Reel of 2000	SN74HC259PWR	HC259
		Reel of 250	SN74HC259PWT	
–55°C to 125°C	CDIP – J	Tube of 25	SNJ54HC259J	SNJ54HC259J
	CFP – W	Tube of 150	SNJ54HC259W	SNJ54HC259W
	LCCC – FK	Tube of 55	SNJ54HC259FK	SNJ54HC259FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

SN54HC259, SN74HC259 8-BIT ADDRESSABLE LATCHES

SCLS 54HC259/74HC259A REV. D SEPTEMBER 2003

description/ordering information (continued)

Four distinct modes of operation are selectable by controlling the clear ($\overline{\text{CLR}}$) and enable ($\overline{\text{G}}$) inputs. In the addressable-latch mode, data at the data-in terminal is written into the addressed latch. The addressed latch follows the data input, with all unaddressed latches remaining in their previous states. In the memory mode, all latches remain in their previous states and are unaffected by the data or address inputs. To eliminate the possibility of entering erroneous data in the latches, $\overline{\text{G}}$ should be held high (inactive) while the address lines are changing. In the 1-of-8 decoding or demultiplexing mode, the addressed output follows the level of the D input with all other outputs low. In the clear mode, all outputs are low and unaffected by the address and data inputs.

Function Tables

FUNCTION

INPUTS		OUTPUT OF ADDRESSED LATCH	EACH OTHER OUTPUT	FUNCTION
CLR	$\overline{\text{G}}$			
H	L	D	Q_{iO}	Addressable latch
H	H	Q_{iO}	Q_{iO}	Memory
L	L	D	L	8-line demultiplexer
L	H	L	L	Clear

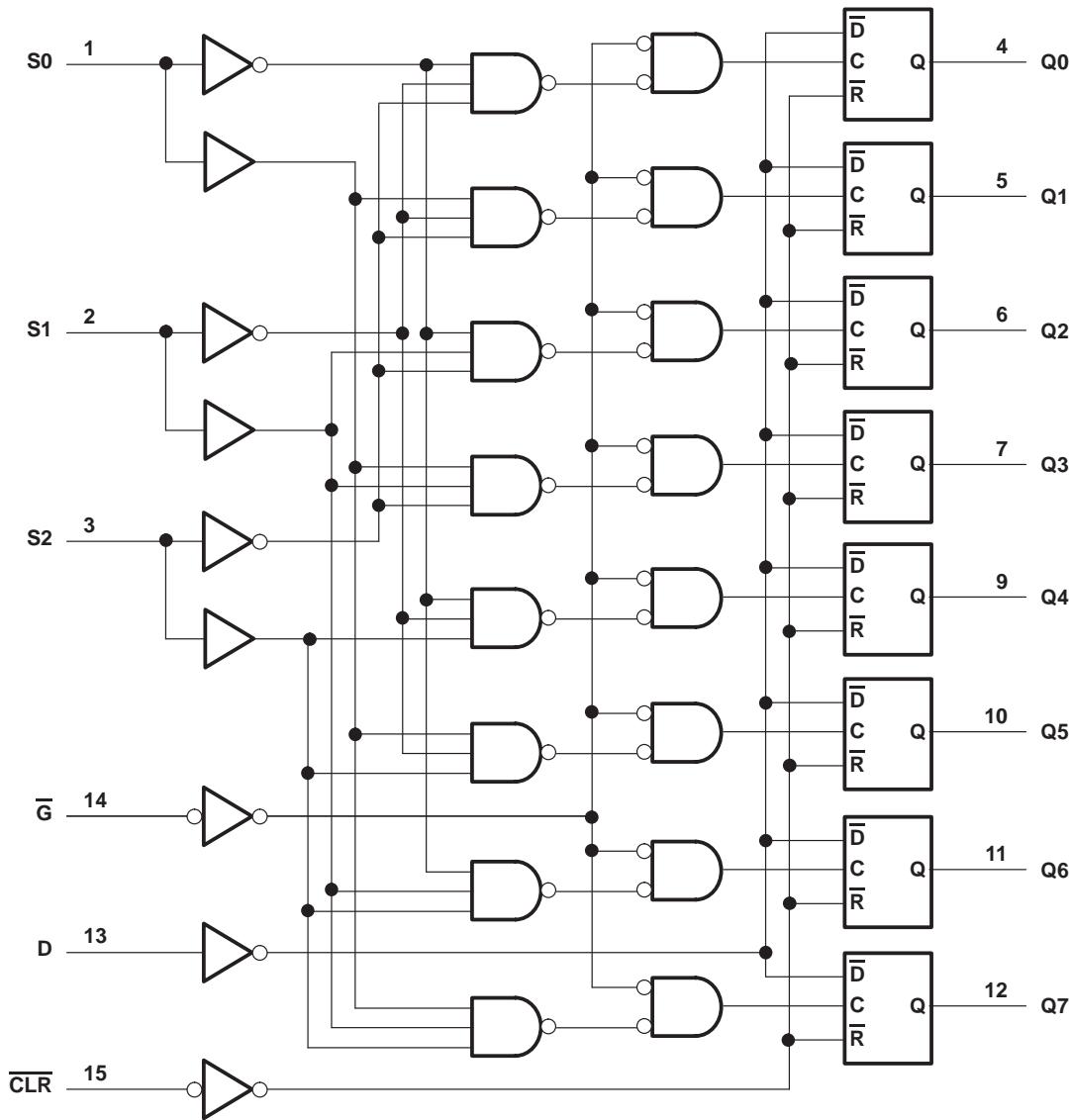
LATCH SELECTION

SELECT INPUTS			LATCH ADDRESSED
S2	S1	S0	
L	L	L	0
L	L	H	1
L	H	L	2
L	H	H	3
H	L	L	4
H	L	H	5
H	H	L	6
H	H	H	7

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logic diagram

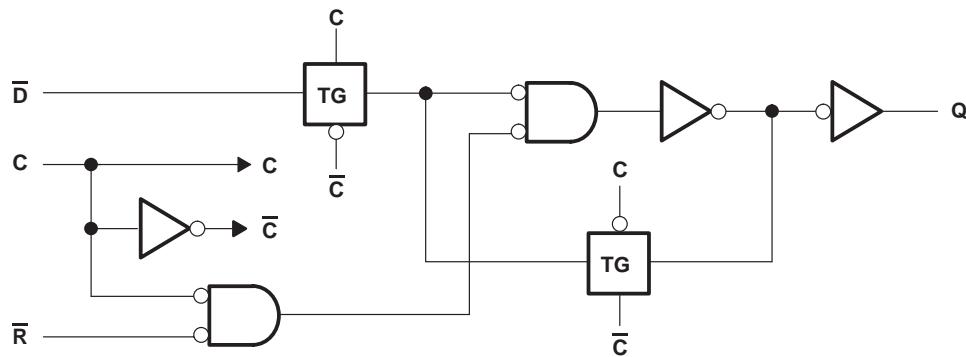


Pin numbers shown are for the D, J, N, NS, PW, and W packages.

SN54HC259, SN74HC259 8-BIT ADDRESSABLE LATCHES

SCLS 944 "PDS FOR TQFP" EDITION 2 SEPTEMBER 2003

[logic diagram](#), each internal latch (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	-0.5 V to 7 V
Input clamp current, I _{IK} (V _I < 0 or V _I > V _{CC}) (see Note 1)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC}) (see Note 1)	±20 mA
Continuous output current, I _O (V _O = 0 to V _{CC})	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ _{JA} (see Note 2): D package	73°C/W
N package	67°C/W
NS package	64°C/W
PW package	108°C/W
Storage temperature range, T _{stg}	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 2. The package thermal impedance is calculated in accordance with JEDEC 51-7.

recommended operating conditions (see Note 3)

		SN54HC259			SN74HC259			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage	2	5	6	2	5	6	V
V _{IH}	High-level input voltage	V _{CC} = 2 V	1.5		1.5			V
		V _{CC} = 4.5 V	3.15		3.15			
		V _{CC} = 6 V	4.2		4.2			
V _{IL}	Low-level input voltage	V _{CC} = 2 V		0.5		0.5		V
		V _{CC} = 4.5 V		1.35		1.35		
		V _{CC} = 6 V		1.8		1.8		
V _I	Input voltage	0	V _{CC}		0	V _{CC}		V
V _O	Output voltage	0	V _{CC}		0	V _{CC}		V
Δt/Δv	Input transition rise/fall time	V _{CC} = 2 V		1000		1000		ns
		V _{CC} = 4.5 V		500		500		
		V _{CC} = 6 V		400		400		
T _A	Operating free-air temperature	-55	125		-40	85		°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54HC259		SN74HC259		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	V _I = V _{IH} or V _{IL}	I _{OH} = -20 µA	2 V	1.9	1.998	1.9		1.9		V
			4.5 V	4.4	4.499	4.4		4.4		
			6 V	5.9	5.999	5.9		5.9		
		I _{OL} = -4 mA	4.5 V	3.98	4.3	3.7		3.84		V
		I _{OL} = -5.2 mA	6 V	5.48	5.8	5.2		5.34		
		2 V	0.002	0.1	0.1		0.1			
V _{OL}	V _I = V _{IH} or V _{IL}	I _{OL} = 20 µA	4.5 V	0.001	0.1	0.1		0.1		V
			6 V	0.001	0.1	0.1		0.1		
			I _{OL} = 4 mA	4.5 V	0.17	0.26	0.4		0.33	
		I _{OL} = 5.2 mA	6 V	0.15	0.26	0.4		0.33		V
I _I	V _I = V _{CC} or 0	6 V		±0.1	±100	±1000		±1000		nA
I _{CC}	V _I = V _{CC} or 0, I _O = 0	6 V			8	160		80		µA
C _i		2 V to 6 V		3	10	10		10		pF

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		V _{CC}	T _A = 25°C		SN54HC259		SN74HC259		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t _w	Pulse duration	CLR low	2 V	80	120		100		ns
			4.5 V	16	24		20		
			6 V	14	20		17		
		G low	2 V	80	120		100		ns
			4.5 V	16	24		20		
			6 V	14	20		17		
t _{su}	Setup time, data or address before G↑	2 V	75		115		95		ns
		4.5 V	15		23		19		
		6 V	13		20		16		
t _h	Hold time, data or address after G↑	2 V	5		5		5		ns
		4.5 V	5		5		5		
		6 V	5		5		5		

SN54HC259, SN74HC259 8-BIT ADDRESSABLE LATCHES

SCLS54HC259-0551901FA "DRAFT" SEPTEMBER 2003

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			SN54HC259	SN74HC259	UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{PHL}	$\overline{\text{CLR}}$	Any Q	2 V	60	150	225	190	190	ns
			4.5 V	18	30	45	38	38	
			6 V	14	26	38	32	32	
t_{pd}	Data	Any Q	2 V	56	130	195	165	165	ns
			4.5 V	17	26	39	33	33	
			6 V	13	22	33	28	28	
	Address	Any Q	2 V	74	200	300	250	250	
			4.5 V	21	40	60	50	50	
			6 V	17	34	51	43	43	
	\overline{G}	Any Q	2 V	66	170	255	215	215	
			4.5 V	20	34	51	43	43	
			6 V	16	29	43	37	37	
t_t		Any	2 V	28	75	110	95	95	ns
			4.5 V	8	15	22	19	19	
			6 V	6	13	19	16	16	

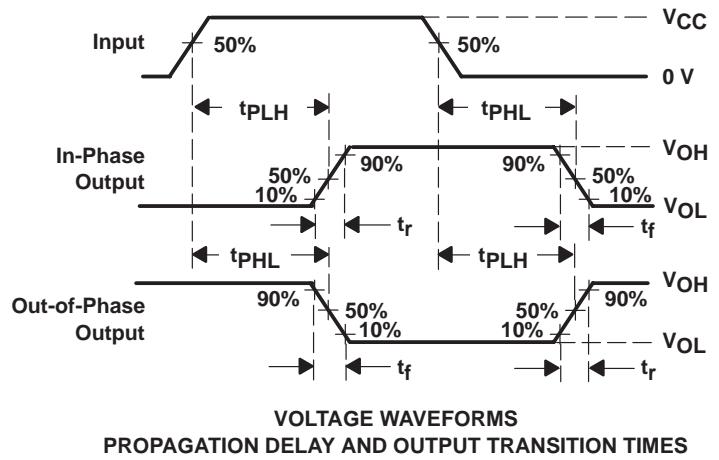
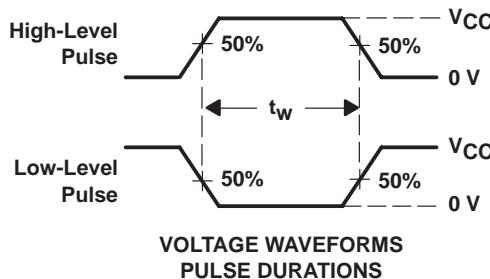
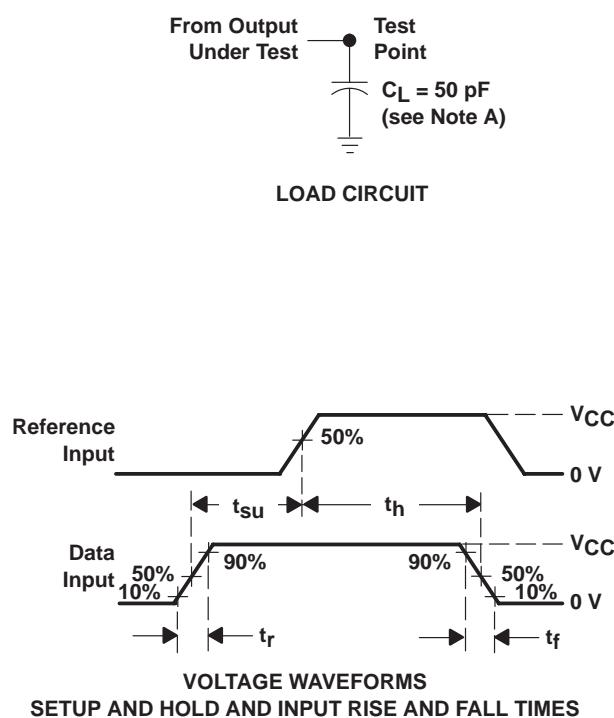
operating characteristics, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance per latch	No load	33	pF

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PARAMETER MEASUREMENT INFORMATION



- NOTES:
- C_L includes probe and test-fixture capacitance.
 - Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR $\leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r = 6 \text{ ns}$, $t_f = 6 \text{ ns}$.
 - The outputs are measured one at a time with one input transition per measurement.
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
85519012A	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
8551901EA	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
8551901FA	ACTIVE	CFP	W	16	1	None	Call TI	Level-NC-NC-NC
JM38510/65402BEA	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
SN54HC259J	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
SN74HC259D	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC259DR	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC259DT	ACTIVE	SOIC	D	16	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC259N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74HC259NSR	ACTIVE	SO	NS	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC259PWLE	OBsolete	TSSOP	PW	16		None	Call TI	Call TI
SN74HC259PWR	ACTIVE	TSSOP	PW	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HC259PWT	ACTIVE	TSSOP	PW	16	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SNJ54HC259FK	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
SNJ54HC259J	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - May not be currently available - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

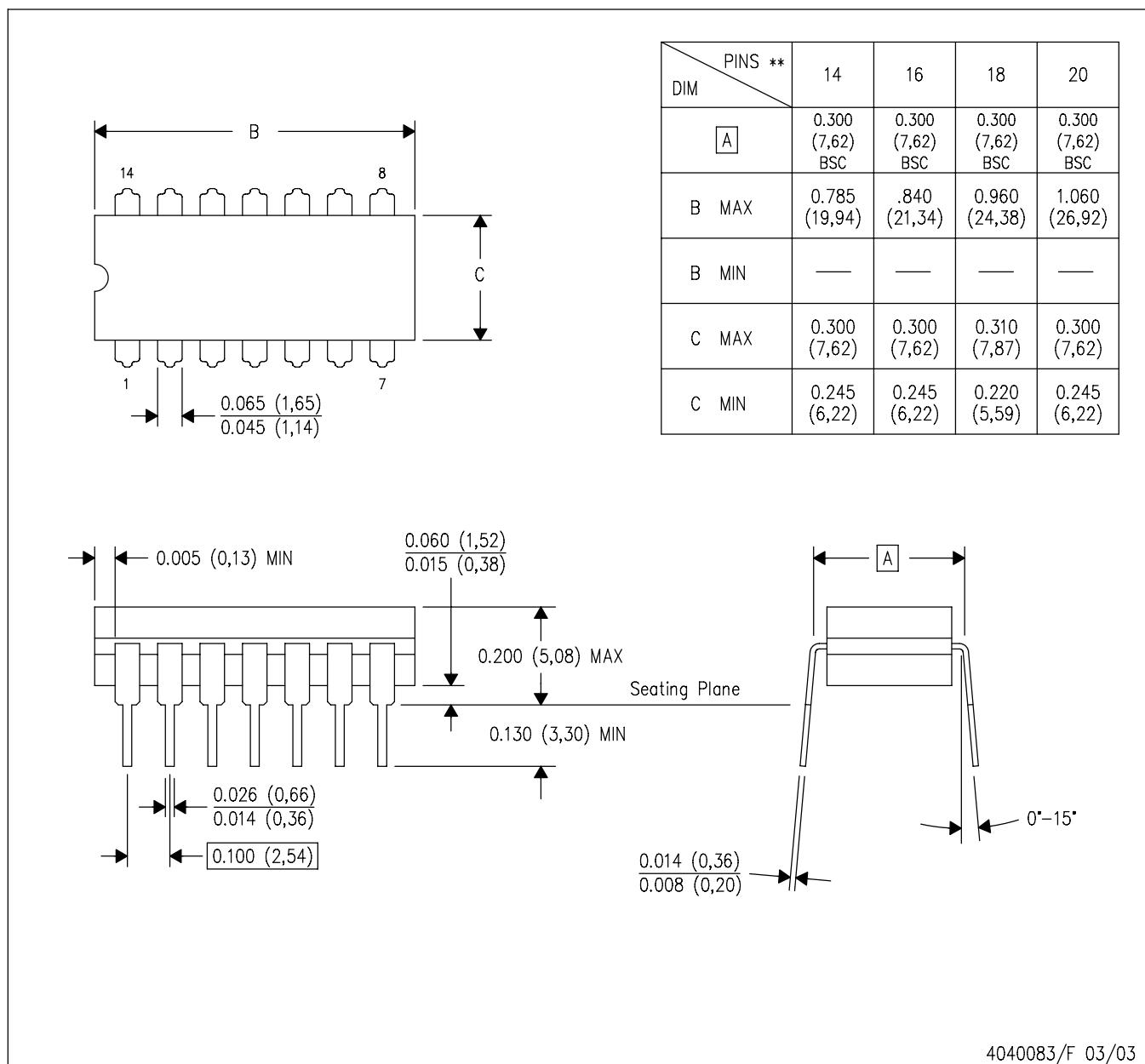
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J (R-GDIP-T**) CERAMIC DUAL IN-LINE PACKAGE

14 LEADS SHOWN

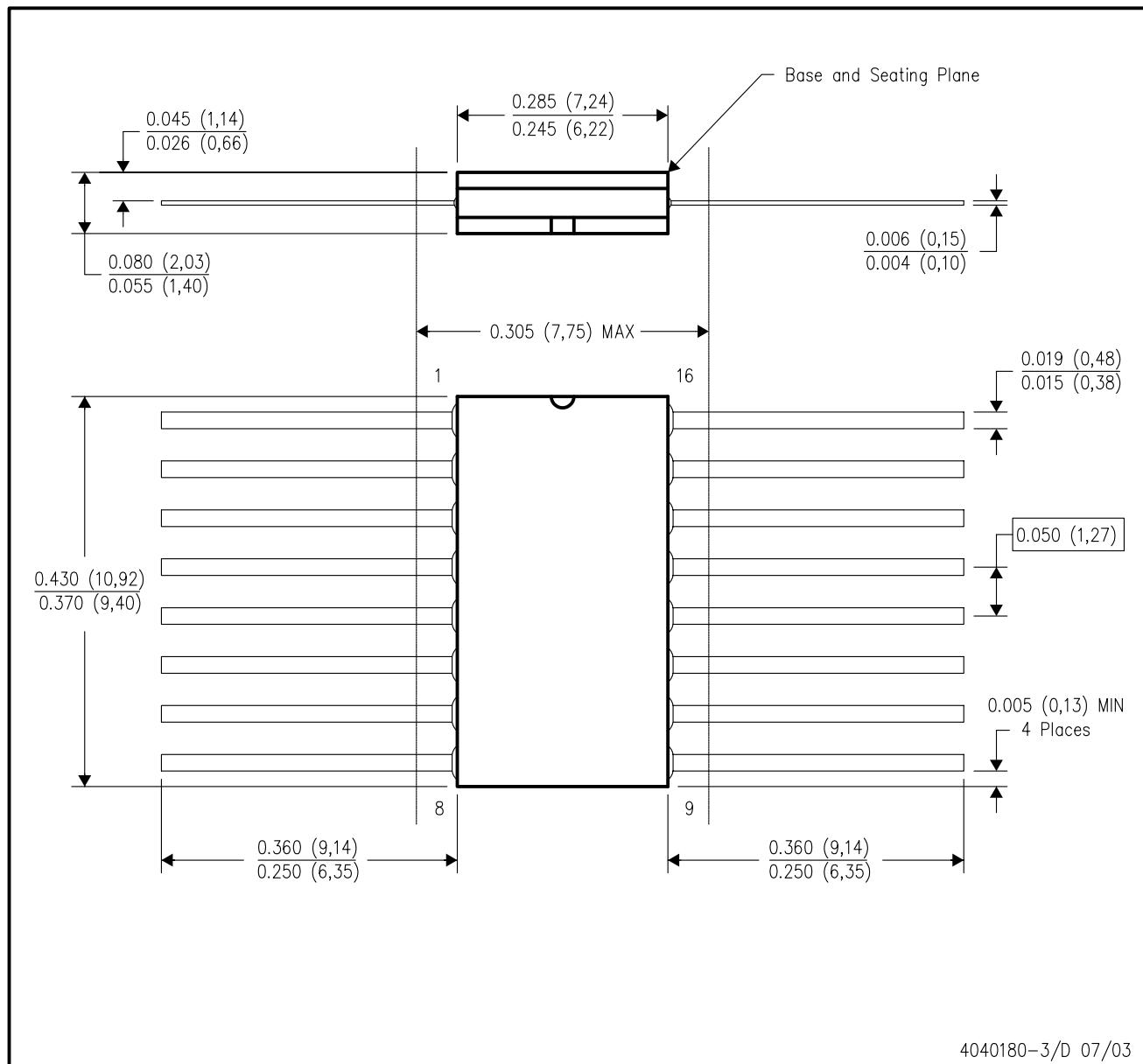


- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

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W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within MIL-STD 1835 GDFP1-F16 and JEDEC MO-092AC

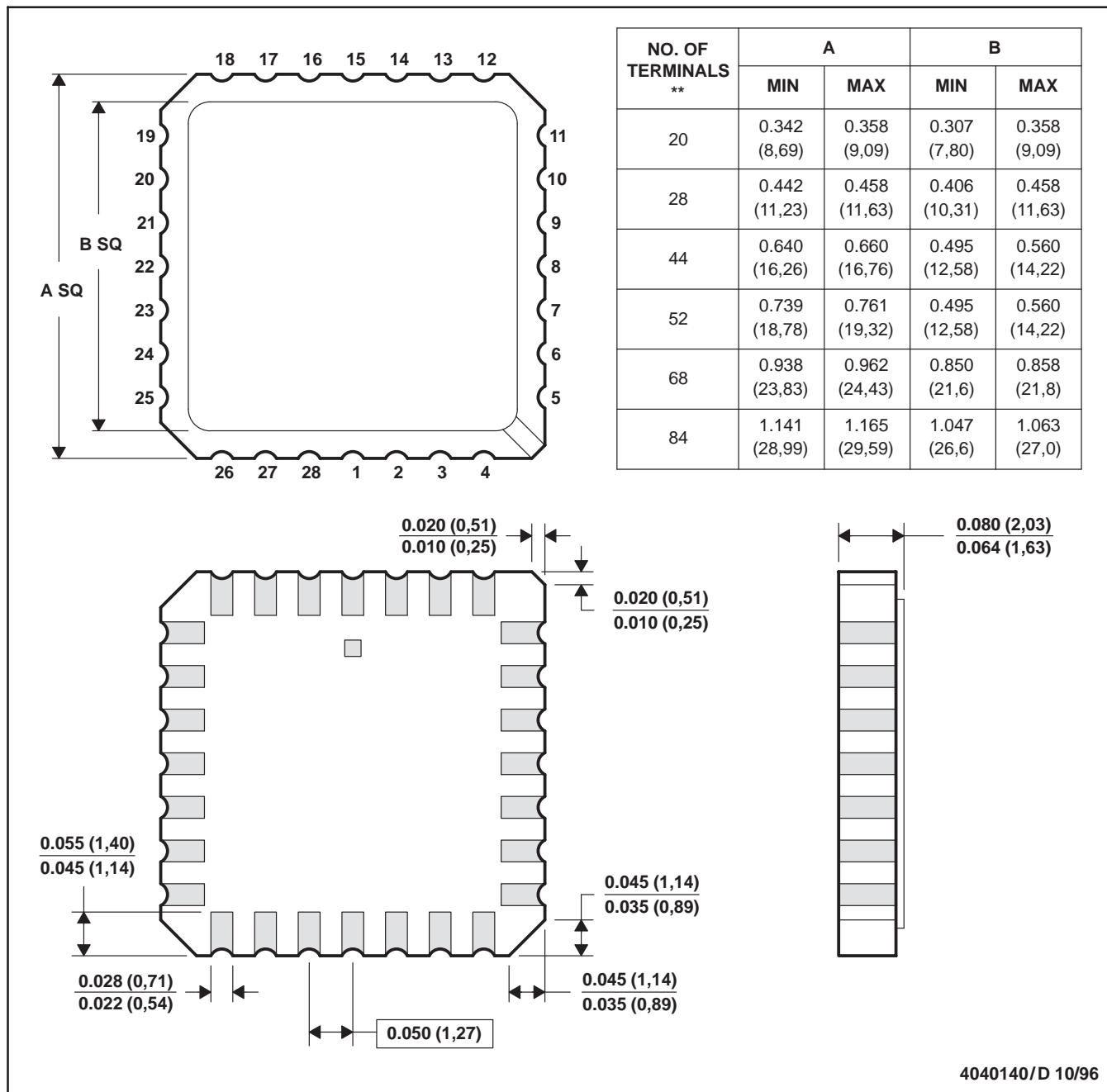
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MLCC006B – OCTOBER 1996

FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



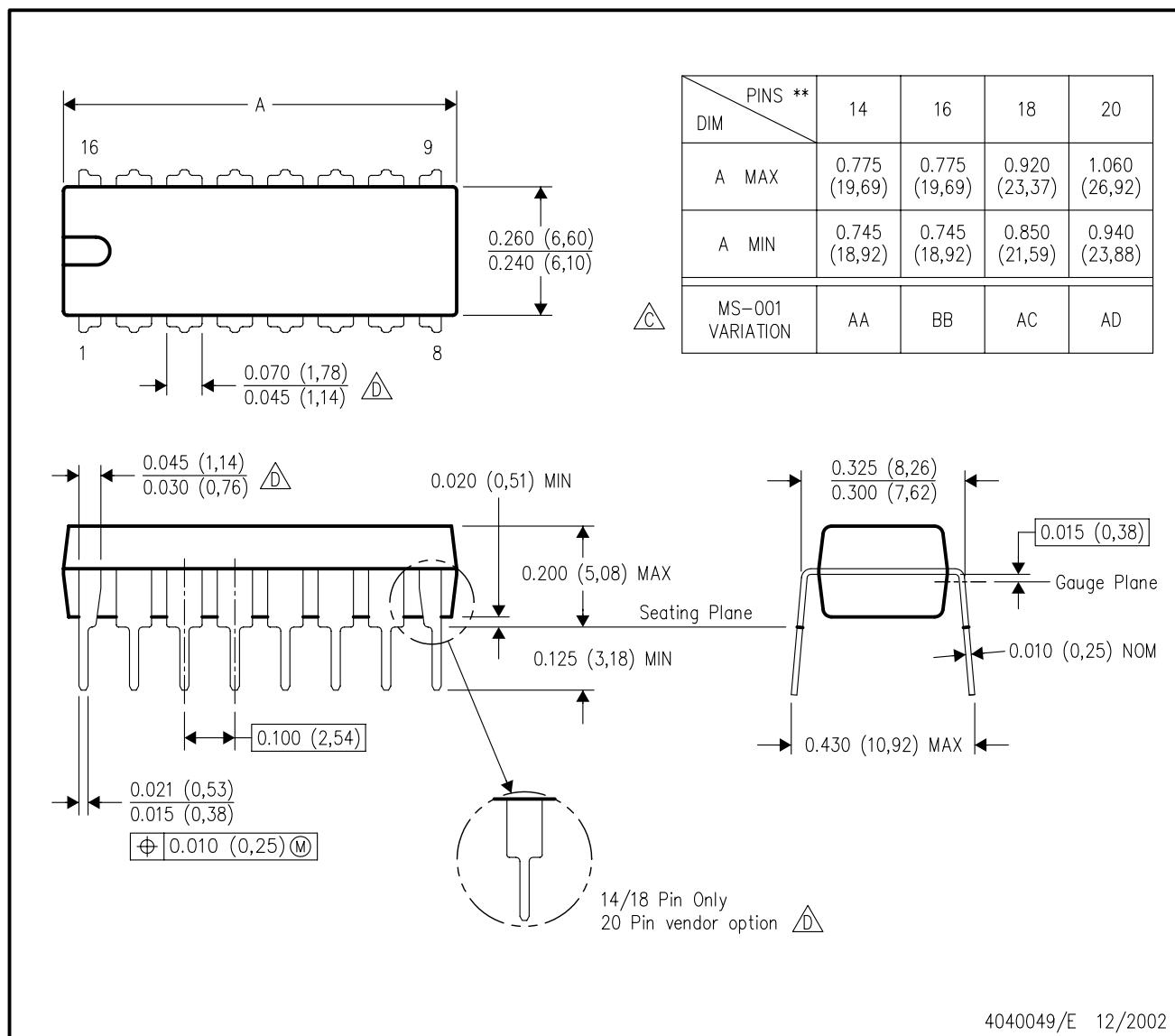
- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - The terminals are gold plated.
 - Falls within JEDEC MS-004

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N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



4040049/E 12/2002

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.

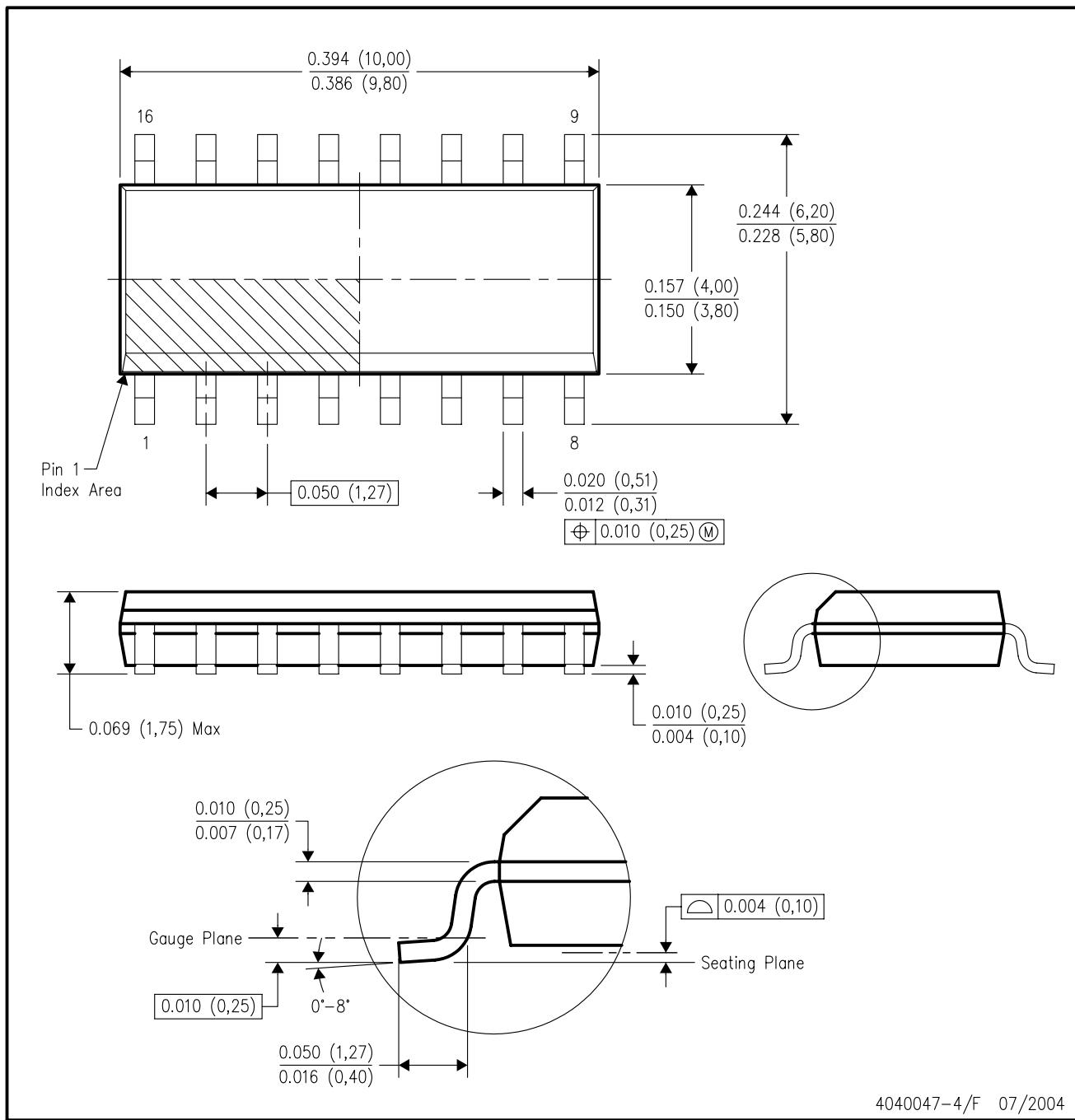
Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

The 20 pin end lead shoulder width is a vendor option, either half or full width.

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D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MS-012 variation AC.

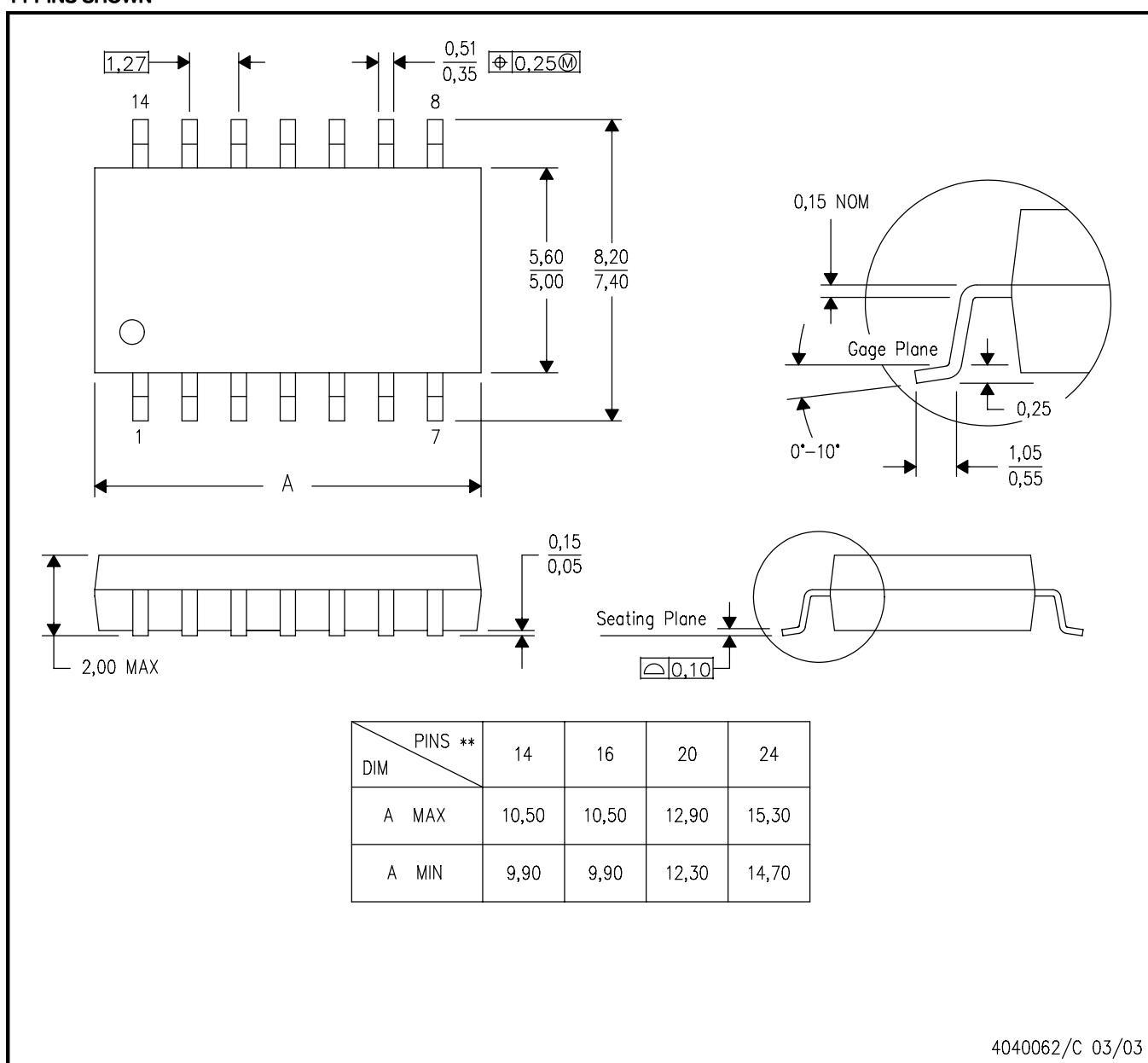
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MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

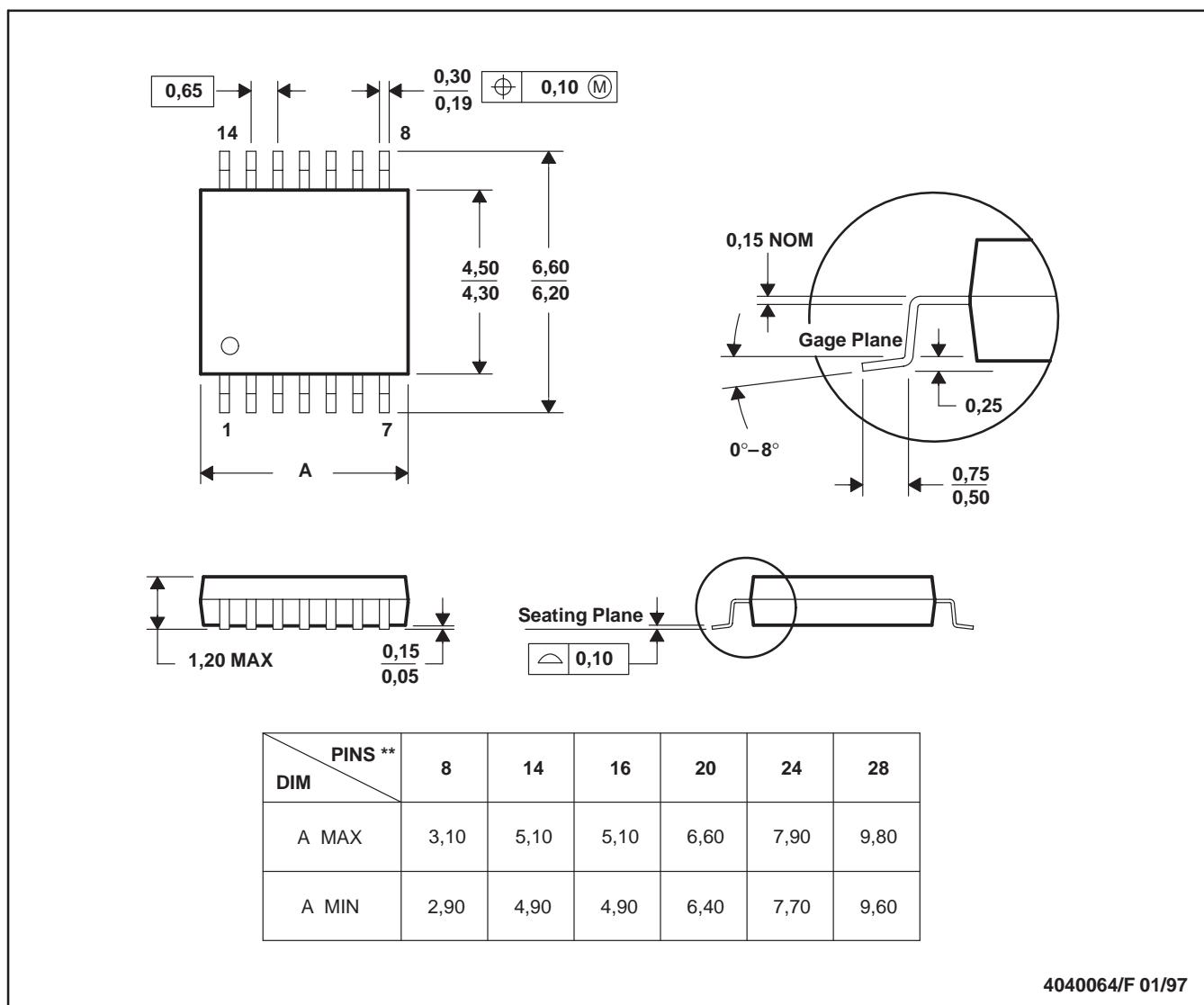
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MTSS001C – JANUARY 1995 – REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 - Falls within JEDEC MO-153

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